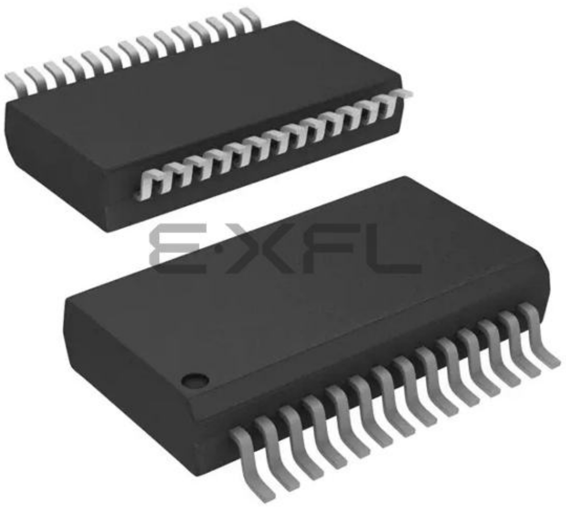

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	8KB (2.75K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 19x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f08km102t-i-ss

3.0 CPU

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the CPU, refer to the *"PIC24F Family Reference Manual"*, **"CPU"** (DS39703).

The PIC24F CPU has a 16-bit (data) modified Harvard architecture with an enhanced instruction set and a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M instructions of user program memory space. A single-cycle instruction prefetch mechanism is used to help maintain throughput and provides predictable execution. All instructions execute in a single cycle, with the exception of instructions that change the program flow, the double-word move (`MOV.D`) instruction and the table instructions. Overhead-free program loop constructs are supported using the `REPEAT` instructions, which are interruptible at any point.

PIC24F devices have sixteen, 16-bit working registers in the programmer's model. Each of the working registers can act as a data, address or address offset register. The 16^{th} working register (W15) operates as a Software Stack Pointer (SSP) for interrupts and calls.

The upper 32 Kbytes of the Data Space (DS) memory map can optionally be mapped into program space at any 16K word boundary of either program memory or data EEPROM memory, defined by the 8-bit Program Space Visibility Page Address (PSVPAG) register. The program to Data Space mapping feature lets any instruction access program space as if it were Data Space.

The Instruction Set Architecture (ISA) has been significantly enhanced beyond that of the PIC18, but maintains an acceptable level of backward compatibility. All PIC18 instructions and addressing modes are supported, either directly, or through simple macros. Many of the ISA enhancements have been driven by compiler efficiency needs.

The core supports Inherent (no operand), Relative, Literal, Memory Direct and three groups of addressing modes. All modes support Register Direct and various Register Indirect modes. Each group offers up to seven addressing modes. Instructions are associated with predefined addressing modes depending upon their functional requirements.

For most instructions, the core is capable of executing a data (or program data) memory read, a working register (data) read, a data memory write and a program (instruction) memory read per instruction cycle. As a result, three parameter instructions can be supported, allowing trinary operations (i.e., A + B = C) to be executed in a single cycle.

A high-speed, 17-bit by 17-bit multiplier has been included to significantly enhance the core arithmetic capability and throughput. The multiplier supports Signed, Unsigned and Mixed mode, 16-bit by 16-bit or 8-bit by 8-bit integer multiplication. All multiply instructions execute in a single cycle.

The 16-bit ALU has been enhanced with integer divide assist hardware that supports an iterative non-restoring divide algorithm. It operates in conjunction with the `REPEAT` instruction looping mechanism and a selection of iterative divide instructions to support 32-bit (or 16-bit), divided by 16-bit integer signed and unsigned division. All divide operations require 19 cycles to complete but are interruptible at any cycle boundary.

The PIC24F has a vectored exception scheme with up to eight sources of non-maskable traps and up to 118 interrupt sources. Each interrupt source can be assigned to one of seven priority levels.

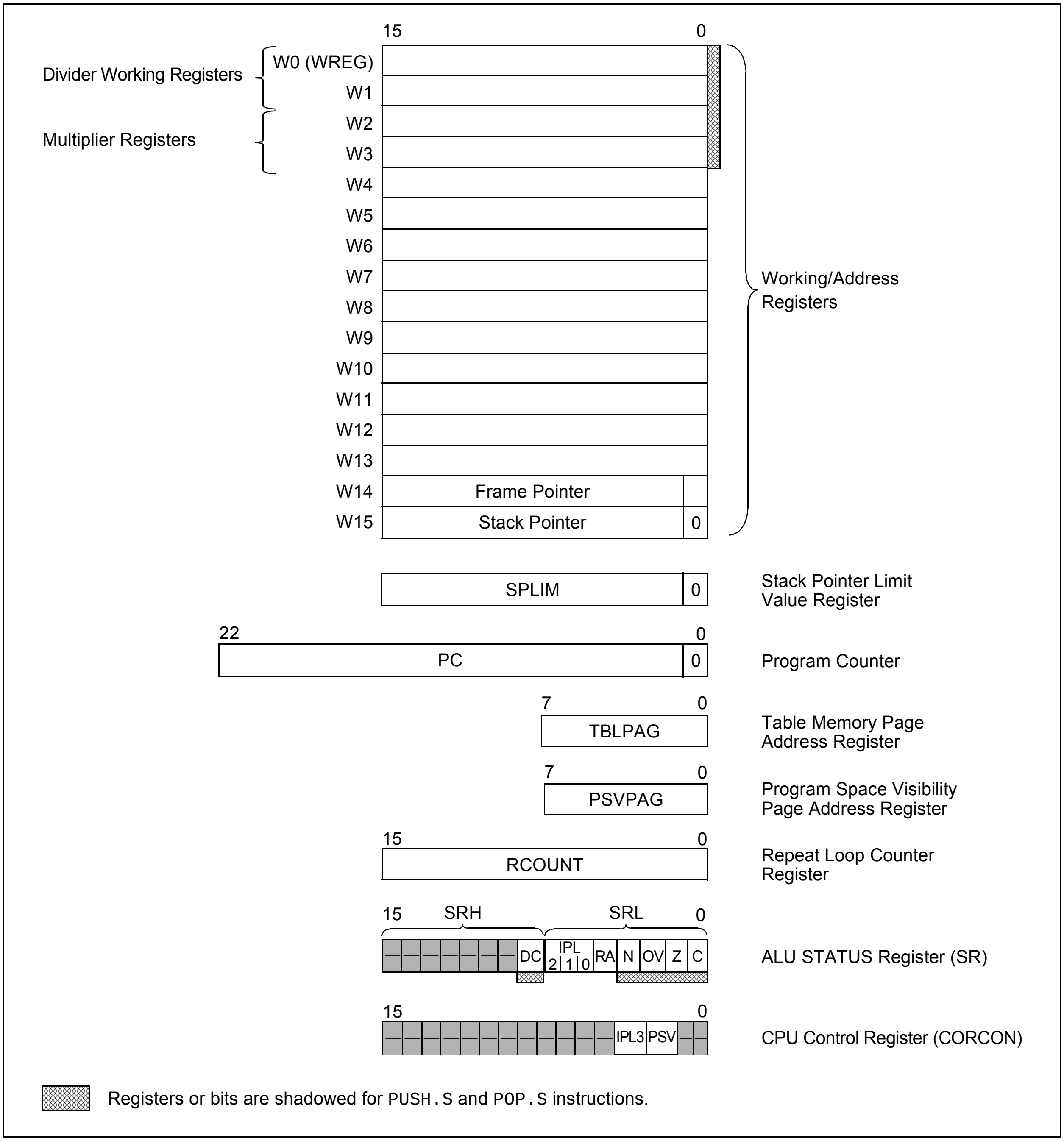
A block diagram of the CPU is illustrated in Figure 3-1.

3.1 Programmer's Model

Figure 3-2 displays the programmer's model for the PIC24F. All registers in the programmer's model are memory mapped and can be manipulated directly by instructions.

Table 3-1 provides a description of each register. All registers associated with the programmer's model are memory mapped.

FIGURE 3-2: PROGRAMMER'S MODEL



3.2 CPU Control Registers

REGISTER 3-1: SR: ALU STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HSC
—	—	—	—	—	—	—	DC
bit 15							bit 8

R/W-0, HSC[1]	R/W-0, HSC[1]	R/W-0, HSC[1]	R-0, HSC	R/W-0, HSC	R/W-0, HSC	R/W-0, HSC	R/W-0, HSC
IPL2[2]	IPL1[2]	IPL0[2]	RA	N	OV	Z	C
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as ‘0’

bit 8 **DC:** ALU Half Carry/Borrow bit
1 = A carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred
0 = No carry-out from the 4th or 8th low-order bit of the result has occurred

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits[1,2]
111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

bit 4 **RA:** REPEAT Loop Active bit
1 = REPEAT loop in progress
0 = REPEAT loop not in progress

bit 3 **N:** ALU Negative bit
1 = Result was negative
0 = Result was non-negative (zero or positive)

bit 2 **OV:** ALU Overflow bit
1 = Overflow occurred for signed (2’s complement) arithmetic in this arithmetic operation
0 = No overflow has occurred

bit 1 **Z:** ALU Zero bit
1 = An operation, which effects the Z bit, has set it at some time in the past
0 = The most recent operation, which effects the Z bit, has cleared it (i.e., a non-zero result)

bit 0 **C:** ALU Carry/$\overline{\text{Borrow}}$ bit
1 = A carry-out from the Most Significant bit (MSb) of the result occurred
0 = No carry-out from the Most Significant bit (MSb) of the result occurred

Note 1: The IPLx Status bits are read-only when NSTDIS (INTCON1<15>) = 1.
2: The IPL<2:0> Status bits are concatenated with the IPL3 bit (CORCON<3>) to form the CPU Interrupt Priority Level (IPL). The value in parentheses indicates the IPL when IPL3 = 1.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® devices and improve Data Space memory usage efficiency, the PIC24F instruction set supports both word and byte operations. As a consequence of byte accessibility, all EA calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] will result in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

Data byte reads will read the complete word, which contains the byte, using the LSB of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, the data memory and the registers are organized as two parallel, byte-wide entities with shared (word) address decode, but separate write lines. Data byte writes only write to the corresponding side of the array or register, which matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap will be generated. If the error occurred on a read, the instruction underway is completed; if it occurred on a write, the instruction will be executed, but the write will not occur. In either case, a trap is then executed, allowing the system and/or user to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the LSB; the MSB is not modified.

A Sign-Extend (`SE`) instruction is provided to allow the users to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, users can clear the MSB of any W register by executing a Zero-Extend (`ZE`) instruction on the appropriate address.

Although most instructions are capable of operating on word or byte data sizes, it should be noted that some instructions operate only on words.

4.2.3 NEAR DATA SPACE

The 8-Kbyte area between 0000h and 1FFFh is referred to as the Near Data Space. Locations in this space are directly addressable via a 13-bit absolute address field within all memory direct instructions. The remainder of the Data Space is addressable indirectly. Additionally, the whole Data Space is addressable using `MOV` instructions, which support Memory Direct Addressing (MDA) with a 16-bit address field. For PIC24FV16KM204 family devices, the entire implemented data memory lies in Near Data Space (NDS).

4.2.4 SFR SPACE

The first 2 Kbytes of the Near Data Space, from 0000h to 07FFh, are primarily occupied with Special Function Registers (SFRs). These are used by the PIC24F core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control and are generally grouped together by that module. Much of the SFR space contains unused addresses; these are read as '`0`'. The SFR space, where the SFRs are actually implemented, is provided in Table 4-2. Each implemented area indicates a 32-byte region where at least one address is implemented as an SFR. A complete listing of implemented SFRs, including their addresses, is provided in Table 4-3 through Table 4-26.

TABLE 4-2: IMPLEMENTED REGIONS OF SFR DATA SPACE

<table>
<tr><th rowspan="2"></th><th colspan="8">SFR Space Address</th></tr>
<tr><th>xx00</th><th>xx20</th><th>xx40</th><th>xx60</th><th>xx80</th><th>xxA0</th><th>xxC0</th><th>xxE0</th></tr>
<tr><td>000h</td><td colspan="3">Core</td><td>ICN</td><td colspan="3">Interrupts</td><td>—</td></tr>
<tr><td>100h</td><td>Timers</td><td>CLC</td><td colspan="6">MCCP/SCCP</td></tr>
<tr><td>200h</td><td>MSSP</td><td>UART</td><td>Op Amp</td><td>DAC</td><td>—</td><td>—</td><td colspan="2">I/O</td></tr>
<tr><td>300h</td><td colspan="4">A/D/CMTU</td><td>—</td><td>—</td><td>—</td><td>—</td></tr>
<tr><td>400h</td><td>—</td><td>—</td><td>—</td><td>—</td><td>—</td><td>—</td><td>—</td><td>ANSEL</td></tr>
<tr><td>500h</td><td>—</td><td>—</td><td>—</td><td>—</td><td>—</td><td>—</td><td>—</td><td>—</td></tr>
<tr><td>600h</td><td>—</td><td>RTCC/Comp</td><td>—</td><td>Band Gap</td><td colspan="4">—</td></tr>
<tr><td>700h</td><td>—</td><td>—</td><td>System/ HLVD</td><td>NVM/PMD</td><td>—</td><td>—</td><td>—</td><td>—</td></tr>
</table>

Legend: — = No implemented SFRs in this block.

REGISTER 8-30: IPC16: INTERRUPT PRIORITY CONTROL REGISTER 16

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	U2ERIP2	U2ERIP1	U2ERIP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	U1ERIP2	U1ERIP1	U1ERIP0	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as ‘0’

bit 10-8 **U2ERIP<2:0>:** UART2 Error Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **U1ERIP<2:0>:** UART1 Error Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as ‘0’

REGISTER 8-35: INTTREG: INTERRUPT CONTROL AND STATUS REGISTER

R-0	U-0	R/W-0	U-0	R-0	R-0	R-0	R-0
CPUIRQ	—	VHOLD	—	ILR3	ILR2	ILR1	ILR0
bit 15							bit 8

U-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
—	VECNUM6	VECNUM5	VECNUM4	VECNUM3	VECNUM2	VECNUM1	VECNUM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CPUIRQ:** Interrupt Request from Interrupt Controller CPU bit
1 = An interrupt request has occurred but has not yet been Acknowledged by the CPU (this will happen when the CPU priority is higher than the interrupt priority)
0 = No interrupt request is left unacknowledged

bit 14 **Unimplemented:** Read as '0'

bit 13 **VHOLD:** Vector Hold bit
Allows Vector Number Capture and Changes which Interrupt is Stored in the VECNUM<6:0> bits:
1 = VECNUM<6:0> will contain the value of the highest priority pending interrupt, instead of the current interrupt
0 = VECNUM<6:0> will contain the value of the last Acknowledged interrupt (last interrupt that has occurred with higher priority than the CPU, even if other interrupts are pending)

bit 12 **Unimplemented:** Read as '0'

bit 11-8 **ILR<3:0>:** New CPU Interrupt Priority Level bits
1111 = CPU Interrupt Priority Level is 15
•
•
•
0001 = CPU Interrupt Priority Level is 1
0000 = CPU Interrupt Priority Level is 0

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **VECNUM<6:0>:** Vector Number of Pending Interrupt bits
0111111 = Interrupt vector pending is Number 135
•
•
•
0000001 = Interrupt vector pending is Number 9
0000000 = Interrupt vector pending is Number 8

9.3 Control Registers

The operation of the oscillator is controlled by three Special Function Registers (SFRs):

- OSCCON
- CLKDIV
- OSCTUN

The OSCCON register (Register 9-1) is the main control register for the oscillator. It controls clock source switching and allows the monitoring of clock sources.

The Clock Divider register (Register 9-2) controls the features associated with Doze mode, as well as the postscaler for the FRC Oscillator.

The FRC Oscillator Tune register (Register 9-3) allows the user to fine-tune the FRC Oscillator over a range of approximately ±5.25%. Each bit increment or decrement changes the factory calibrated frequency of the FRC Oscillator by a fixed amount.

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER

U-0	R-0, HSC	R-0, HSC	R-0, HSC	U-0	R/W-x(1)	R/W-x(1)	R/W-x(1)
—	COSC2	COSC1	COSC0	—	NOSC2	NOSC1	NOSC0
bit 15							bit 8

R/SO-0, HSC	U-0	R-0, HSC(2)	U-0	R/CO-0, HS	R/W-0(3)	R/W-0	R/W-0
CLKLOCK	—	LOCK	—	CF	SOSCDRV	SOSCEN	OSWEN
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
HS = Hardware Settable bit	CO = Clearable Only bit	SO = Settable Only bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **COSC<2:0>:** Current Oscillator Selection bits
111 = 8 MHz Fast RC Oscillator with Postscaler (FRCDIV)
110 = 500 kHz Low-Power Fast RC Oscillator (FRC) with Postscaler (LPFRCDIV)
101 = Low-Power RC Oscillator (LPRC)
100 = Secondary Oscillator (SOSC)
011 = Primary Oscillator with PLL module (XTPLL, HSPLL, ECPLL)
010 = Primary Oscillator (XT, HS, EC)
001 = 8 MHz FRC Oscillator with Postscaler and PLL module (FRCPLL)
000 = 8 MHz FRC Oscillator (FRC)

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **NOSC<2:0>:** New Oscillator Selection bits(1)
111 = 8 MHz Fast RC Oscillator with Postscaler (FRCDIV)
110 = 500 kHz Low-Power Fast RC Oscillator (FRC) with Postscaler (LPFRCDIV)
101 = Low-Power RC Oscillator (LPRC)
100 = Secondary Oscillator (SOSC)
011 = Primary Oscillator with PLL module (XTPLL, HSPLL, ECPLL)
010 = Primary Oscillator (XT, HS, EC)
001 = 8 MHz FRC Oscillator with Postscaler and PLL module (FRCPLL)
000 = 8 MHz FRC Oscillator (FRC)

Note 1: Reset values for these bits are determined by the FNOSCx Configuration bits.
2: This bit also resets to ‘0’ during any valid clock switch or whenever a non-PLL Clock mode is selected.
3: When SOSC is selected to run from a digital clock input, rather than an external crystal (SOSCSRC = 0), this bit has no effect.

14.0 MASTER SYNCHRONOUS SERIAL PORT (MSSP)

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on MSSP, refer to the *"PIC24F Family Reference Manual"*.

The Master Synchronous Serial Port (MSSP) module is an 8-bit serial interface, useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, Shift registers, display drivers, A/D Converters, etc. The MSSP module can operate in one of two modes:

- Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit (I^2C™)
  - Full Master mode
  - Slave mode (with general address call)

The SPI interface supports these modes in hardware:

- Master mode
- Slave mode
- Daisy-Chaining Operation in Slave mode
- Synchronized Slave Operation

The I^2C interface supports the following modes in hardware:

- Master mode
- Multi-Master mode
- Slave mode with 10-Bit and 7-Bit Addressing and Address Masking
- Byte NACKing
- Selectable Address and Data Hold, and Interrupt Masking

14.1 I/O Pin Configuration for SPI

In SPI Master mode, the MSSP module will assert control over any pins associated with the SDOx and SCKx outputs. This does not automatically disable other digital functions associated with the pin and may result in the module driving the digital I/O port inputs. To prevent this, the MSSP module outputs must be disconnected from their output pins while the module is in SPI Master mode. While disabling the module temporarily may be an option, it may not be a practical solution in all applications.

The SDOx and SCKx outputs for the module can be selectively disabled by using the SDOxDIS and SCKxDIS bits in the PADCFG1 register (Register 14-10). Setting the bit disconnects the corresponding output for a particular module from its assigned pin.

REGISTER 15-3: UxTXREG: UARTx TRANSMIT REGISTER

U-x	U-x	U-x	U-x	U-x	U-x	U-x	W-x
—	—	—	—	—	—	—	UTX8
bit 15							bit 8

W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x
UTX7	UTX6	UTX5	UTX4	UTX3	UTX2	UTX1	UTX0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9	**Unimplemented:** Read as ‘0’
bit 8	**UTX8:** Data of the Transmitted Character bit (in 9-bit mode)
bit 7-0	**UTX<7:0>:** Data of the Transmitted Character bits

REGISTER 15-4: UxRXREG: UARTx RECEIVE REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R-0, HSC
—	—	—	—	—	—	—	URX8
bit 15							bit 8

R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC
URX7	URX6	URX5	URX4	URX3	URX2	URX1	URX0
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9	**Unimplemented:** Read as ‘0’
bit 8	**URX8:** Data of the Received Character bit (in 9-bit mode)
bit 7-0	**URX<7:0>:** Data of the Received Character bits

16.3 Calibration

The real-time crystal input can be calibrated using the periodic auto-adjust feature. When properly calibrated, the RTCC can provide an error of less than 3 seconds per month. This is accomplished by finding the number of error clock pulses and storing the value into the lower half of the RCFGCAL register. The 8-bit signed value, loaded into the lower half of RCFGCAL, is multiplied by four and will be either added or subtracted from the RTCC timer, once every minute. Refer to the steps below for RTCC calibration:

1. Using another timer resource on the device, the user must find the error of the 32.768 kHz crystal.
2. Once the error is known, it must be converted to the number of error clock pulses per minute.
3. a) If the oscillator is faster than ideal (negative result from Step 2), the RCFGCAL register value must be negative. This causes the specified number of clock pulses to be subtracted from the timer counter, once every minute.

   b) If the oscillator is slower than ideal (positive result from Step 2), the RCFGCAL register value must be positive. This causes the specified number of clock pulses to be subtracted from the timer counter, once every minute.

EQUATION 16-1:

(Ideal Frequency† – Measured Frequency) * 60 = Clocks per Minute

† Ideal Frequency = 32,768 Hz

Writes to the lower half of the RCFGCAL register should only occur when the timer is turned off, or immediately after the rising edge of the seconds pulse, except when SECONDS = 00, 15, 30 or 45. This is due to the auto-adjust of the RTCC at 15 second intervals.

Note:	It is up to the user to include, in the error value, the initial error of the crystal: drift due to temperature and drift due to crystal aging.

16.4 Alarm

- Configurable from half second to one year
- Enabled using the ALRMEN bit (ALCFGRPT<15>)
- One-time alarm and repeat alarm options are available

16.4.1 CONFIGURING THE ALARM

The alarm feature is enabled using the ALRMEN bit. This bit is cleared when an alarm is issued. Writes to ALRMVAL should only take place when ALRMEN = `0`.

As shown in Figure 16-2, the interval selection of the alarm is configured through the AMASKx bits (ALCFGRPT<13:10>). These bits determine which and how many digits of the alarm must match the clock value for the alarm to occur.

The alarm can also be configured to repeat based on a preconfigured interval. The amount of times this occurs, once the alarm is enabled, is stored in the ARPT<7:0> bits (ALCFGRPT<7:0>). When the value of the ARPTx bits equals 00h and the CHIME bit (ALCFGRPT<14>) is cleared, the repeat function is disabled, and only a single alarm will occur. The alarm can be repeated up to 255 times by loading ARPT<7:0> with FFh.

After each alarm is issued, the value of the ARPTx bits is decremented by one. Once the value has reached 00h, the alarm will be issued one last time, after which, the ALRMEN bit will be cleared automatically and the alarm will turn off.

Indefinite repetition of the alarm can occur if the CHIME bit = `1`. Instead of the alarm being disabled when the value of the ARPTx bits reaches 00h, it rolls over to FFh and continues counting indefinitely while CHIME is set.

16.4.2 ALARM INTERRUPT

At every alarm event, an interrupt is generated. In addition, an alarm pulse output is provided that operates at half the frequency of the alarm. This output is completely synchronous to the RTCC clock and can be used as a Trigger clock to other peripherals.

Note:	Changing any of the registers, other than the RCFGCAL and ALCFGRPT registers, and the CHIME bit while the alarm is enabled (ALRMEN = `1`), can result in a false alarm event leading to a false alarm interrupt. To avoid a false alarm event, the timer and alarm values should only be changed while the alarm is disabled (ALRMEN = `0`). It is recommended that the ALCFGRPT register and CHIME bit be changed when RTCSYNC = `0`.

REGISTER 19-4: AD1CON5: A/D CONTROL REGISTER 5

R/W-0	R/W-0	R/W-0	R/W-0	r-0	U-0	R/W-0	R/W-0
ASEN[(1)]	LPEN	CTMREQ	BGREQ	r	—	ASINT1	ASINT0
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	WM1	WM0	CM1	CM0
bit 7							bit 0

Legend:	r = Reserved bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ASEN:** A/D Auto-Scan Enable bit[(1)]
- 1 = Auto-scan is enabled
- 0 = Auto-scan is disabled

bit 14 **LPEN:** A/D Low-Power Enable bit
- 1 = Returns to Low-Power mode after scan
- 0 = Remains in Full-Power mode after scan

bit 13 **CTMREQ:** CTMU Request bit
- 1 = CTMU is enabled when the A/D is enabled and active
- 0 = CTMU is not enabled by the A/D

bit 12 **BGREQ:** Band Gap Request bit
- 1 = Band gap is enabled when the A/D is enabled and active
- 0 = Band gap is not enabled by the A/D

bit 11 **Reserved:** Maintain as ‘0’

bit 10 **Unimplemented:** Read as ‘0’

bit 9-8 **ASINT<1:0>:** Auto-Scan (Threshold Detect) Interrupt Mode bits
- 11 = Interrupt after a Threshold Detect sequence has completed and a valid compare has occurred
- 10 = Interrupt after a valid compare has occurred
- 01 = Interrupt after a Threshold Detect sequence has completed
- 00 = No interrupt

bit 7-4 **Unimplemented:** Read as ‘0’

bit 3-2 **WM<1:0>:** A/D Write Mode bits
- 11 = Reserved
- 10 = Auto-compare only (conversion results are not saved, but interrupts are generated when a valid match, as defined by the CMx and ASINTx bits, occurs)
- 01 = Convert and save (conversion results are saved to locations as determined by the register bits when a match, as defined by the CMx bits, occurs)
- 00 = Legacy operation (conversion data is saved to a location determined by the buffer register bits)

bit 1-0 **CM<1:0>:** A/D Compare Mode bits
- 11 = Outside Window mode (valid match occurs if the conversion result is outside of the window defined by the corresponding buffer pair)
- 10 = Inside Window mode (valid match occurs if the conversion result is inside the window defined by the corresponding buffer pair)
- 01 = Greater Than mode (valid match occurs if the result is greater than the value in the corresponding buffer register)
- 00 = Less Than mode (valid match occurs if the result is less than the value in the corresponding buffer register)

Note 1: When using auto-scan with Threshold Detect (ASEN = 1), do not configure the sample clock source to Auto-Convert mode (SSRC<3:0> = 7). Any other available SSRC selection is valid. To use auto-convert as the sample clock source (SSRC<3:0> = 7), make sure ASEN is cleared.

REGISTER 20-2: BUFCON0: INTERNAL VOLTAGE REFERENCE CONTROL REGISTER 0

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-1
—	—	—	—	—	—	BUFREF1	BUFREF0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-2 **Unimplemented:** Read as ‘0’

bit 1-0 **BUFREF<1:0>:** Internal Voltage Reference Select bits
11 = Reference output is set at 4 * BGBUF1(1)
10 = Reference output is set at 2 * BGBUF1(2)
01 = Reference output is set at BGBUF1
00 = Reserved, do not use

Note 1: Available only on PIC24FV16KMXXX devices. The reference may not be within specifications for VDD below specified levels; see Table 27-15 for minimum VDD limits.

2: The reference may not be within specifications for VDD below specified levels; see Table 27-15 for minimum VDD limits.

24.3 Pulse Generation and Delay

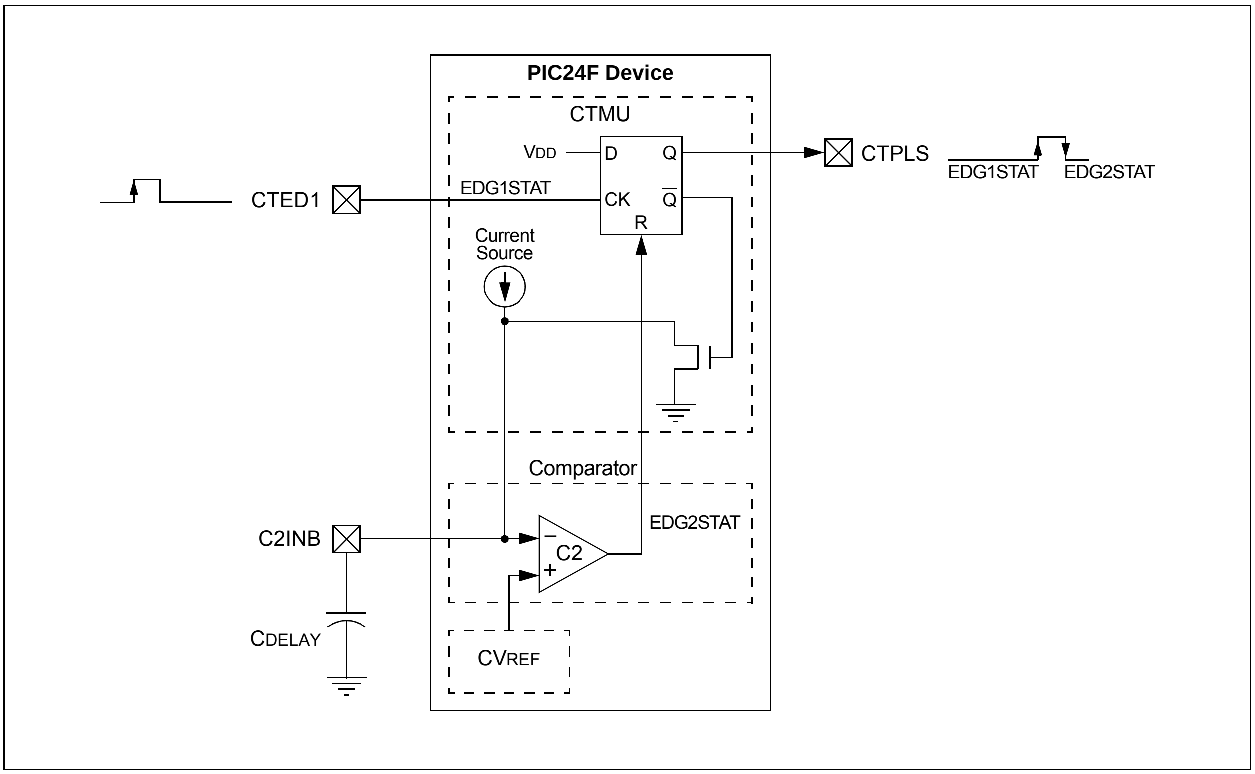
The CTMU module can also generate an output pulse with edges that are not synchronous with the device's system clock. More specifically, it can generate a pulse with a programmable delay from an edge event input to the module.

When the module is configured for pulse generation delay by setting the TGEN bit (CTMUCON1L<12>), the internal current source is connected to the B input of Comparator 2. A Capacitor (CDELAY) is connected to the Comparator 2 pin, C2INB, and the Comparator Voltage Reference, CVREF, is connected to C2INA. CVREF is then configured for a specific trip point. The module begins to charge CDELAY when an edge event is detected. While CVREF is greater than the voltage on CDELAY, the CTPLS pin is high.

When the voltage on CDELAY equals CVREF, CTPLS goes low. With Comparator 2 configured as the second edge, this stops the CTMU from charging. In this state event, the CTMU automatically connects to ground. The IDISSEN bit doesn't need to be set and cleared before the next CTPLS cycle.

Figure 24-3 illustrates the external connections for pulse generation, as well as the relationship of the different analog modules required. While CTED1 is shown as the input pulse source, other options are available. A detailed discussion on pulse generation with the CTMU module is provided in the "*PIC24F Family Reference Manual*".

FIGURE 24-3: TYPICAL CONNECTIONS AND INTERNAL CONFIGURATION FOR PULSE DELAY GENERATION



REGISTER 25-9: DEVREV: DEVICE REVISION REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 23							bit 16

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R	R	R	R
—	—	—	—	REV3	REV2	REV1	REV0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 23-4 **Unimplemented:** Read as ‘0’

bit 3-0 **REV<3:0>:** Minor Revision Identifier bits

TABLE 27-1: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
Operating Junction Temperature Range	T_J	-40	—	+140	°C
Operating Ambient Temperature Range	T_A	-40	—	+125	°C
Power Dissipation Internal Chip Power Dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \Sigma I_{OH})$ I/O Pin Power Dissipation: $P_{I/O} = \Sigma(\{V_{DD} - V_{OH}\} \times I_{OH}) + \Sigma(V_{OL} \times I_{OL})$	P_D	$P_{INT} + P_{I/O}$			W
Maximum Allowed Power Dissipation	P_{DMAX}	$(T_J - T_A)/\theta_{JA}$			W

TABLE 27-2: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit	Notes
Package Thermal Resistance, 20-Pin PDIP	θ_{JA}	62.4	—	°C/W	1
Package Thermal Resistance, 28-Pin SPDIP	θ_{JA}	60	—	°C/W	1
Package Thermal Resistance, 20-Pin SSOP	θ_{JA}	108	—	°C/W	1
Package Thermal Resistance, 28-Pin SSOP	θ_{JA}	71	—	°C/W	1
Package Thermal Resistance, 20-Pin SOIC	θ_{JA}	75	—	°C/W	1
Package Thermal Resistance, 28-Pin SOIC	θ_{JA}	80.2	—	°C/W	1
Package Thermal Resistance, 20-Pin QFN	θ_{JA}	43	—	°C/W	1
Package Thermal Resistance, 28-Pin QFN	θ_{JA}	32	—	°C/W	1
Package Thermal Resistance, 44-Pin QFN	θ_{JA}	29	—	°C/W	1
Package Thermal Resistance, 44-Pin TQFP	θ_{JA}	40	—	°C/W	1
Package Thermal Resistance, 48-Pin UQFN	θ_{JA}	41	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θ_{JA}) numbers are achieved by package simulations.

TABLE 27-3: DC CHARACTERISTICS: TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KMXXX) 2.0V to 5.5V (PIC24FV16KMXXX)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DC10	V_{DD}	**Supply Voltage**	1.8	—	3.6	V	For PIC24F devices
			2.0	—	5.5	V	For PIC24FV devices
DC12	V_{DR}	**RAM Data Retention Voltage(2)**	1.6	—	—	V	For PIC24F devices
			1.8	—	—	V	For PIC24FV devices
DC16	V_{POR}	**V_{DD} Start Voltage** to Ensure Internal Power-on Reset Signal	V_{SS}	—	0.7	V	
DC17	SV_{DD}	**V_{DD} Rise Rate** to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	0-3.3V in 0.1s 0-2.5V in 60 ms

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: This is the limit to which V_{DD} can be lowered without losing RAM data.

TABLE 27-7: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS		Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KMXXX) 2.0V to 5.5V (PIC24FV16KMXXX) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Device**	**Typical**	**Max**	**Units**	**Conditions**	
Idle Current (IIDLE)						
DC40	PIC24FV16KMXXX	120	200	μA	2.0V	0.5 MIPS, FOSC = 1 MHz(1)
		160	430	μA	5.0V	
	PIC24F16KMXXX	50	100	μA	1.8V	
		90	370	μA	3.3V	
DC42	PIC24FV16KMXXX	165	—	μA	2.0V	1 MIPS, FOSC = 2 MHz(1)
		260	—	μA	5.0V	
	PIC24F16KMXXX	95	—	μA	1.8V	
		180	—	μA	3.3V	
DC44	PIC24FV16KMXXX	3.1	6.5	mA	5.0V	16 MIPS, FOSC = 32 MHz(1)
	PIC24F16KMXXX	2.9	6.0	mA	3.3V	
DC46	PIC24FV16KMXXX	0.65	—	mA	2.0V	FRC (4 MIPS), FOSC = 8 MHz
		1.0	—	mA	5.0V	
	PIC24F16KMXXX	0.55	—	mA	1.8V	
		1.0	—	mA	3.3V	
DC50	PIC24FV16KMXXX	42	200	μA	2.0V	LPRC (15.5 KIPS), FOSC = 31 kHz
		65	225	μA	5.0V	
	PIC24F16KMXXX	2.2	18	μA	1.8V	
		4.0	40	μA	3.3V	

Legend: Unshaded rows represent PIC24F16KMXXX devices and shaded rows represent PIC24FV16KMXXX devices.

Note 1: The oscillator is in External Clock mode (FOSCSEL<2:0> = `010`, FOSC<1:0> = `00`).

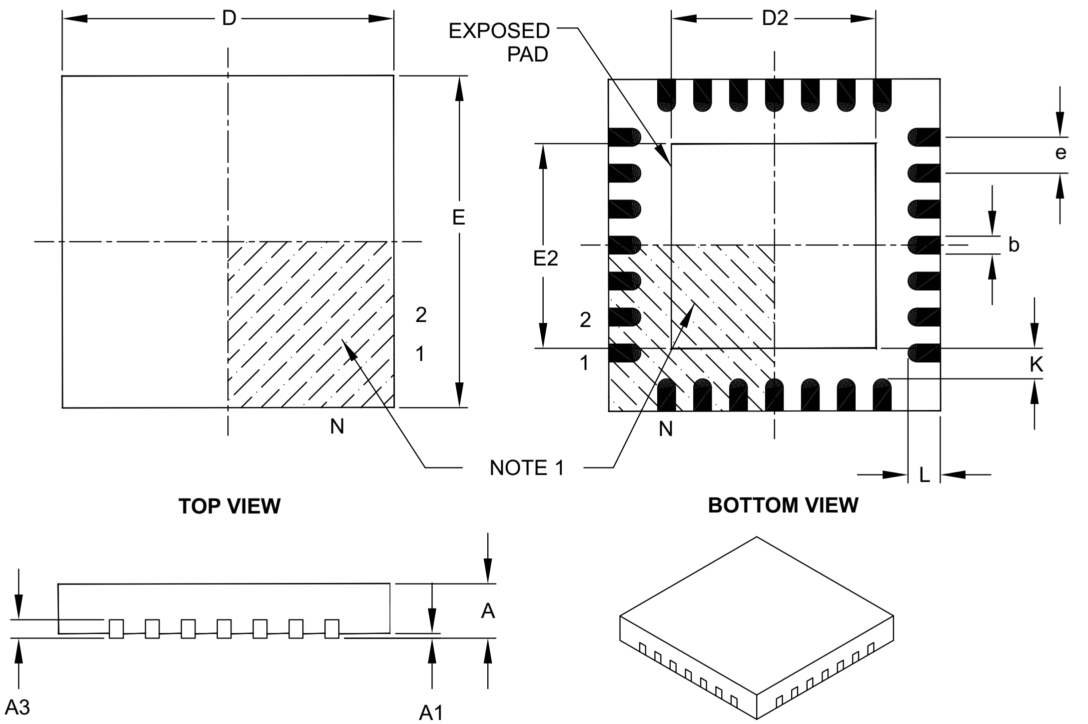
TABLE 27-39: 8-BIT DIGITAL-TO-ANALOG CONVERTER SPECIFICATIONS

AC CHARACTERISTICS			**Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KM204)** **2.0V to 5.5V (PIC24FV16KM204)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Comments**
		Resolution	8	—	—	bits	
		DACREF<1:0> Input Voltage Range	AVSS + 1.8	—	AVDD	V	
		Differential Linearity Error (DNL)	—	—	±0.5	LSb	
		Integral Linearity Error (INL)	—	—	±1.5	LSb	
		Offset Error	—	—	±0.5	LSb	
		Gain Error	—	—	±3.0	LSb	
		Monotonicity	—	—	—	—	**(Note 1)**
		Output Voltage Range	AVSS + 50	AVSS + 5 to AVDD – 5	AVDD – 50	mV	0.5V input overdrive, no output loading
		Slew Rate	—	5	—	V/µs	
		Settling Time	—	10	—	µs	

Note 1: DAC output voltage never decreases with an increase in the data code.

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.20
Contact Width	b	0.23	0.30	0.35
Contact Length	L	0.50	0.55	0.70
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

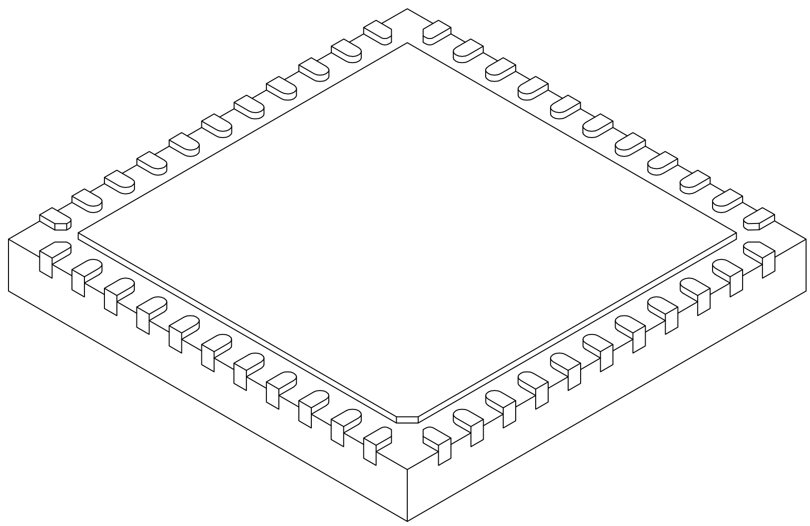
    BSC: Basic Dimension. Theoretically exact value shown without tolerances.

    REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105B

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103C Sheet 2 of 2

NOTES: